

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
UNITED STATES RECEIVING OFFICE (RO/US)

In re Application of:	Francis Bourrieres, et al	<i>L. Nelson</i> <i>#3/Prel Amt A</i> <i>11-1-01</i>
U.S. Nat'l Stage of Int'l App. No.:	PCT/FR00/00018	
Int'l Filing Date:	6 January 2000	
For:	Method For Making Electronic Modules With Ball-Connector Or With Integrated Preforms Capable Of Being Soldered On A Printed Circuit And Implementing Device	

Box PCT
ATTN: EO/US
Commissioner for Patents
Washington, D.C. 20231

Docket No.: N48.2-9735

PRELIMINARY AMENDMENT

Before calculating the fees in this application, please amend the above-identified application as indicated below:

In the Abstract:

Insert the abstract page 19, enclosed herewith.

In the Claims:

Replace original claims 1-9 with claims 1-9 as follows:

AI

1) (Amended) Method for producing an electronic module in the shape of a ball housing combining a network of balls (7) or geometrically identical preform connectors or shield system and surface-mounted components (2) on the same side of a substrate (1), thus making this module directly connectable by soldering to a printed circuit (3), wherein soldering cream (8) is deposited simultaneously for the components and the connecting ball or shield system located on the same surface;

said components are transferred onto the corresponding mounting lands;

the ball connectors with a diameter greater than the height of said components are transferred collectively onto the lands of the same side intended for them by an appropriate device; and

a single re-melting cycle permits simultaneous soldering of the components and the connecting balls or shields onto the substrate.